

#### Is Now Part of



## ON Semiconductor®

# To learn more about ON Semiconductor, please visit our website at <a href="https://www.onsemi.com">www.onsemi.com</a>

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (\_), the underscore (\_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (\_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at <a href="www.onsemi.com">www.onsemi.com</a>. Please email any questions regarding the system integration to Fairchild <a href="guestions@onsemi.com">guestions@onsemi.com</a>.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



### FDC6303N Digital FET, Dual N-Channel

#### **General Description**

These dual N-Channel logic level enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is especially tailored to minimize on-state resistance. This device has been designed especially for low voltage applications as a replacement for digital transistors in load switching applications. Since bias resistors are not required this one N-Channel FET can replace several digital transistors with different bias resistors like the IMHxA series.

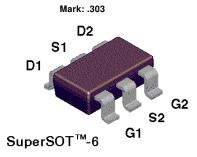
#### **Features**

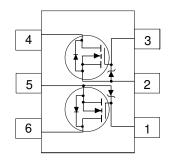
■ 25 V, 0.68 A continuous, 2 A Peak.

$$\begin{split} R_{\text{DS(ON)}} &= 0.6 \; \Omega \; @ \; \text{V}_{\text{GS}} = 2.7 \; \text{V} \\ R_{\text{DS(ON)}} &= 0.45 \; \Omega \; @ \; \text{V}_{\text{GS}} = 4.5 \; \text{V}. \end{split}$$

- Very low level gate drive requirements allowing direct operation in 3V circuits. V<sub>GS(th)</sub> < 1.5 V.</li>
- Gate-Source Zener for ESD ruggedness. >6kV Human Body Model
- Replace multiple NPN digital transistors (IMHxA series) with one DMOS FET.







**Absolute Maximum Ratings**  $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	FDC6303N	Units
V <sub>DSS</sub>	Drain-Source Voltage	25	V
V <sub>GSS</sub>	Gate-Source Voltage	8	V
I <sub>D</sub>	Drain Current - Continuous	0.68	A
	- Pulsed	2	
$P_{\scriptscriptstyle D}$	Maximum Power Dissipation (Note 1a)	0.9	W
	(Note 1b)	0.7	
$T_J$ , $T_{STG}$	Operating and Storage Temperature Range	-55 to 150	°C
ESD	Electrostatic Discharge Rating MIL-STD-883D Human Body Model (100pf / 1500 Ohm)	6.0	kV
THERMA	L CHARACTERISTICS		•
$R_{\theta^{JA}}$	Thermal Resistance, Junction-to-Ambient (Note 1a)	140	°C/W
R <sub>euc</sub>	Thermal Resistance, Junction-to-Case (Note 1)	60	°C/W

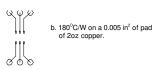
Symbol	Parameter	Conditions	Min	Тур	Max	Units
OFF CHAR	ACTERISTICS					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \ I_{D} = 250 \mu\text{A}$	25			V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient	$I_D = 250 \mu A$ , Referenced to $25 ^{\circ} C$		26		mV /°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 20 \text{ V}, \ V_{GS} = 0 \text{ V}$			1	μΑ
		T <sub>J</sub> = 55°C			10	μΑ
GSS	Gate - Body Leakage Current	$V_{GS} = 8 \text{ V}, \ V_{DS} = 0 \text{ V}$			100	nA
	CTERISTICS (Note 2)	1 00 00		1		
$\Delta V_{GS(th)}/\Delta T_{J}$	Gate Threshold Voltage Temp.Coefficient	$I_D = 250 \mu\text{A}$ , Referenced to $25^{\circ}\text{C}$		-2.6		mV /°C
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, \ I_{D} = 250 \ \mu A$	0.65	0.8	1.5	٧
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 0.5 \text{ A}$		0.33	0.45	Ω
()		T <sub>.1</sub> =125°C		0.52	0.8	
		$V_{GS} = 2.7 \text{ V}, I_D = 0.2 \text{ A}$		0.44	0.6	
D(ON)	On-State Drain Current	$V_{GS} = 2.7 \text{ V}, \ V_{DS} = 5 \text{ V}$	0.5			Α
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_{D} = 0.5 \text{ A}$		1.45		S
DYNAMIC C	HARACTERISTICS					
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		50		pF
C <sub>oss</sub>	Output Capacitance			28		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			9		pF
SWITCHING	CHARACTERISTICS (Note 2)	•				
D(on)	Turn - On Delay Time	$V_{DD} = 6 \text{ V}, \ I_{D} = 0.5 \text{ A},$ $V_{GS} = 4.5 \text{ V}, \ R_{GEN} = 50 \Omega$		3	6	ns
r	Turn - On Rise Time			8.5	18	ns
·D(off)	Turn - Off Delay Time			17	30	ns
i f	Turn - Off Fall Time			13	25	ns
Q <sub>g</sub>	Total Gate Charge	$V_{DS} = 5 \text{ V}, \ I_{D} = 0.5 \text{ A}, \ V_{GS} = 4.5 \text{ V}$		1.64	2.3	nC
$Q_{gs}$	Gate-Source Charge			0.38		nC
$Q_{gd}$	Gate-Drain Charge			0.45		nC
DRAIN-SOU	RCE DIODE CHARACTERISTICS AND MA	XIMUM RATINGS				
s	Maximum Continuous Source Current				0.3	Α
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 0.5 \text{ A (Note 2)}$		0.83	1.2	V

Notes:

1. R<sub>BM</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>BM</sub> is guaranteed by design while  $R_{\theta^{CA}}$  is determined by the user's board design.  $R_{\theta^{JA}}$  shown below for single device operation on FR-4 in still air.



a. 140°C/W on a 0.125 in² pad of 2oz copper.



2. Pulse Test: Pulse Width  $\leq$  300 $\mu$ s, Duty Cycle  $\leq$  2.0%.

#### **Typical Electrical Characteristics**

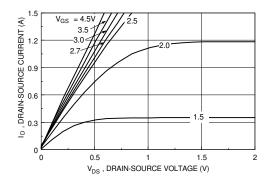


Figure 1. On-Region Characteristics.

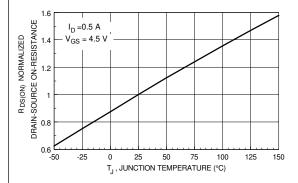


Figure 3. On-Resistance Variation with Temperature.

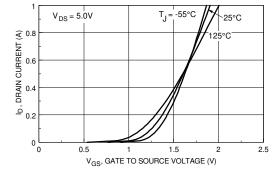


Figure 5. Transfer Characteristics.

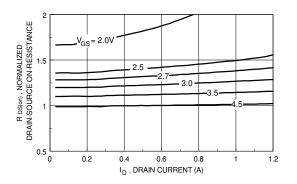


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

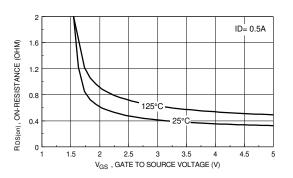


Figure 4. On Resistance Variation with Gate-To- Source Voltage.

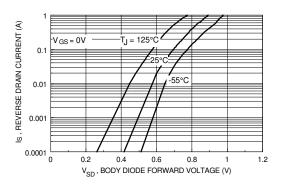


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

#### **Typical Electrical And Thermal Characteristics**

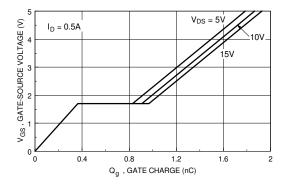


Figure 7. Gate Charge Characteristics.

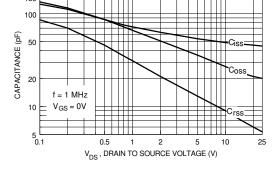


Figure 8. Capacitance Characteristics.

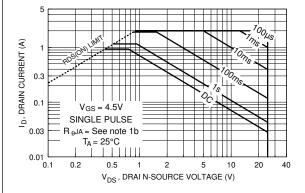


Figure 9. Maximum Safe Operating Area.

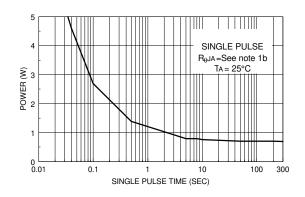


Figure 10. Single Pulse Maximum Power Dissipation.

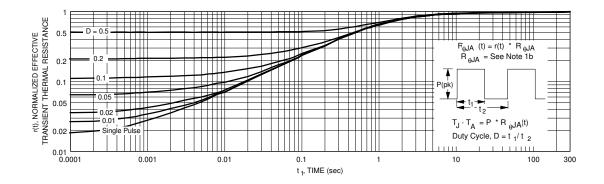


Figure 11. Transient Thermal Response Curve.

Note: Thermal characterization performed using the conditions described in note 1b.Transient thermal response will change depending on the circuit board design.

#### **TRADEMARKS**

The following are registered and unregistered trademarks Fairchild Semiconductor owns or is authorized to use and is not intended to be an exhaustive list of all such trademarks.

FAST ® SMART START™  $VCX^{TM}$ ACEx™ OPTOLOGIC™ STAR\*POWER™ FASTr™ Bottomless™ OPTOPLANAR™ Stealth™ CoolFET<sup>TM</sup> FRFET™ PACMAN<sup>TM</sup> SuperSOT™-3 CROSSVOLT™ GlobalOptoisolator™ POP™ SuperSOT™-6 DenseTrench™ GTO™ Power247™  $\mathsf{HiSeC^{\mathsf{TM}}}$ SuperSOT™-8 DOME™ PowerTrench® SyncFET™ ISOPLANAR™ EcoSPARK™ QFET™ TinyLogic™ E<sup>2</sup>CMOS<sup>TM</sup> LittleFET™  $OS^{TM}$ EnSigna™ MicroFET™ TruTranslation™ QT Optoelectronics™ MicroPak™ UHC™ FACT™ Quiet Series™ UltraFET® FACT Quiet Series™ MICROWIRE™ SILENT SWITCHER®

STAR\*POWER is used under license

#### **DISCLAIMER**

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS. NOR THE RIGHTS OF OTHERS.

#### LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- 1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in significant injury to the
- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

#### PRODUCT STATUS DEFINITIONS

#### **Definition of Terms**

Datasheet Identification	Product Status	Definition	
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.	
Preliminary	First Production	This datasheet contains preliminary data, and supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.	
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.	
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.	

Rev. H4

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <a href="www.onsemi.com/site/pdf/Patent-Marking.pdf">www.onsemi.com/site/pdf/Patent-Marking.pdf</a>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hol

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5817–1050 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative